

Power Inductor

Automotive Grade

AKPB Series



Overview

Power inductors are passive electronic components used in various circuits to store energy in a magnetic field when electrical current flows through them. They are critical in filtering, energy storage, and noise suppression in power electronic systems. They are designed to handle higher currents and are optimized for minimal power loss and thermal efficiency.

Benefits

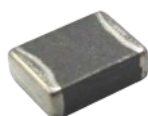
1. Automotive grade available
2. Energy Storage, Efficiently stores and transfers energy in DC-DC converters and power supplies.
3. High Current Handling, Supports high current capacity with minimal losses, ensuring thermal stability.
4. Compact and Efficient Design, Advanced materials and construction enable miniaturization without sacrificing performance, ideal for space-constrained designs.

Applications

1. Automotive Systems for ADAS, infotainment.
2. Industrial Equipment: Robotics, power tools, industrial automation, and IoT devices.
3. DC-DC converters, inverters, and battery management systems.
4. Base stations, 5G infrastructure, and signal processing systems.
5. Consumer Electronics: Smartphones, laptops, tablets, wearable devices, and gaming consoles.

Product Information

Series	L (mm)	W(mm)	T (mm)	Inductance (μH)
AKPB	1.6	0.8	0.8	0.47 ~ 4.7
	2.0	1.25	1.0	
	2.0	1.6	1.0	
	2.5	2.0	1.0	

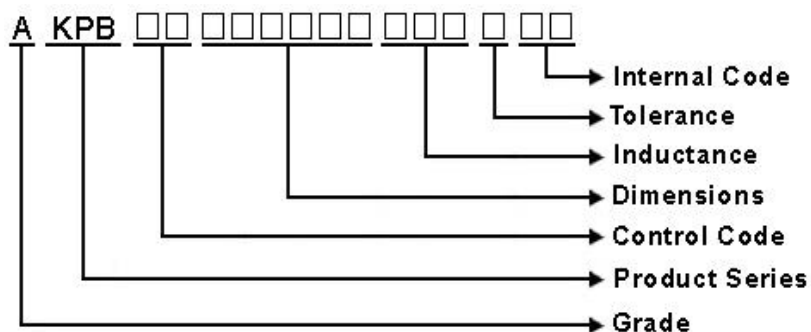


AKPB00201610 Series Specification

AEC-Q200

1 Scope: This specification applies to Multilayer Chip Inductors for Automotive Electronics based on AEC-Q200 except for Power train and Safety.

2 Part Numbering:



3 Rating:

Operating Temperature: - 5 5 °C ~ 1 2 5 °C

Storage Temperature: - 5 5 °C ~ 1 2 5 °C(after PCB)

- 5 °C~4 0 °C, Humidity 4 0 %~7 0 %(before PCB)

4 Marking:

No Marking

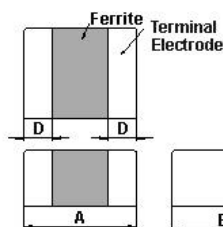
5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

AKPB00201610 Series Specification

AEC-Q200

6 Configuration and Dimensions:



Dimensions in mm

TYPE	201610
A	2.0±0.2
B	1.6±0.2
C	1.0 Max.
D	0.5±0.3

Net Weight (grms)	
Size Code	Net Weight (grms)
201610	0.0168

7 Electrical Characteristics:

Part No.	Inductance (uH)	Test Freq.	RDC (Ω)±25%	Isat (mA)Max.	I _{rms} (mA)Max.		Tolerance (±%)
					85°C*1	125°C*1	
AKPB00201610R47□A6	0.47	3MHz,200mV	0.06	1200	1600	1200	20,30
AKPB002016101R0□A6	1	3MHz,200mV	0.085	850	1300	950	20,30
AKPB002016101R5□A6	1.5	3MHz,200mV	0.11	600	1200	900	20,30
AKPB002016102R2□A6	2.2	3MHz,200mV	0.11	400	1200	900	20,30
AKPB002016103R3□A6	3.3	3MHz,200mV	0.12	350	850	625	20,30
AKPB002016104R7□A6	4.7	3MHz,200mV	0.14	200	1100	800	20,30

NOTE: □-tolerance M=±20% / T=±30%

1. Operating temperature range - 55°C ~ 125°C

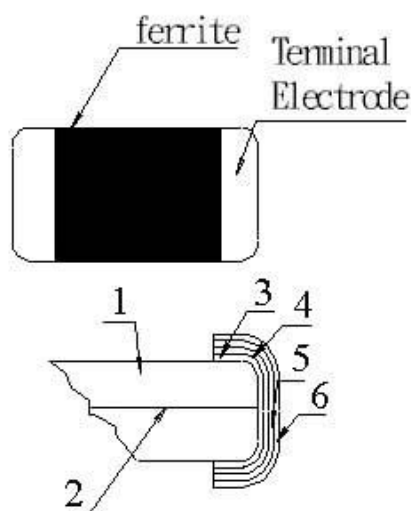
2. Isat for Inductance drop 30% from its value without current.

3. I_{rms} for When applied current to the Products, temperature rise caused by self-generated heat shall be limited to 40 °C max

4. As for the Rated current marked with *1, Rated Current is depending on the operating temperature

8 AKPB00201610 Series

8.1 Construction:

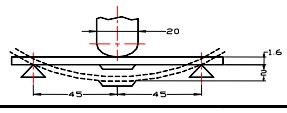
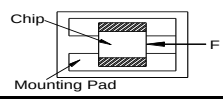


8.2 Material List:

NO	PART	MATERIAL
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

9 Reliability Of Ferrite Multilayer power inductors

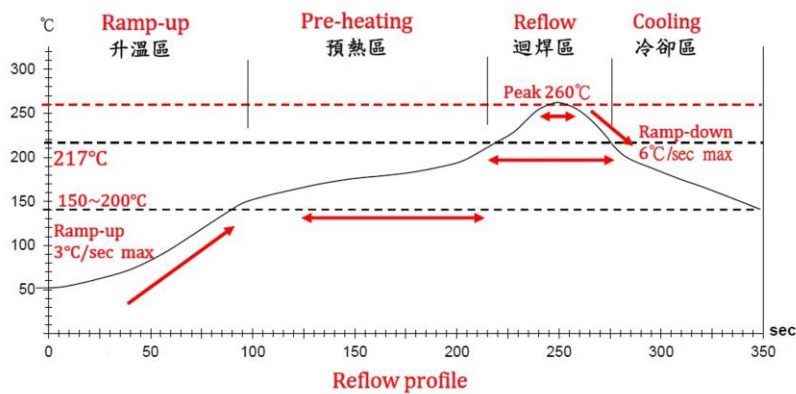
1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Board Flex	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Refer to AEC-Q200-005 Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 60 sec 
1-1-2	Resistance to Soldering Heat	Appearance: No damage Impedance change shall be within±30%	Refer to MIL-STD-202 Method 210 Pre-heating: 150-200°C, 60-100 sec Above 217°C, 60-150 secs Peak Temperature: 260±5°C, 20-40 sec Cycles : 2 times
1-1-3	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Refer to J-STD-002 Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5°C (Pb-Free) Immersion Time: 4±1sec
1-1-4	Terminal Strength Test	The chip must not damage the terminal electrode and the ferrite	Refer to AEC-Q200-006 Test device shall be soldered on the substrate Force 2N for 60±1 seconds for 0603 series Force 5N for 60±1 seconds for 1005 series Force 10N for 60±1 seconds for 1608 series Force 1.8Kg for 60±1 seconds for the other series. 
1-1-5	Vibration Test	Appearance: No damage Impedance change shall be within±30%	Refer to MIL-STD-202 Method 204 Vibration waveform: Sine waveform Vibration frequency: 10Hz~2000Hz Vibration acceleration: 5g 10Hz~20KHz and back to 10Hz should be down in 20 minutes Duration of test: 12 cycles each of 3 orientations, 20 minutes for each cycle, 12 hr total Vibration axes: X, Y & Z
1-1-6	Mechanical Shock Test	Appearance: No damage Impedance change shall be within±30%	Refer to MIL-STD-202 Method 213 Units are non-operating. Pulse shape : Half-sine waveform Impact acceleration : 100 g Pulse duration : 6 ms Number of shocks : 18 shocks (3 shocks for each face)
1-1-7	Physical Dimension	The chip must not damage the terminal electrode and the ferrite	Refer to JESD22 Method JB-100 Verify physical dimensions to the applicable device specification. Note : User(s) and Suppliers spec. Electrical Test not Required.
1-1-8	Resistance to Solvent	There must be no change in appearance or obliteration of marking	Refer to MIL-STD-202 Method 215 Inductors must withstand 6 minutes of alcohol or water.
1-1-9	ESD	Appearance: No damage Impedance change shall be within±30%	Refer to AEC-Q200-002 ESD Rank 2 :2kV

9 Reliability Of Ferrite Multilayer power inductors

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Impedance change shall be within $\pm 30\%$ or meet spec	Refer to JESD Method JA-104 Total cycles: 1000 cycles 30 minutes exposure to -40°C 30 minutes exposure to 125°C 1 min. maximum transition between temperatures Measured after exposure in the room condition for 24hrs
1-2-2	Biased Humidity Resistance		Refer to MIL-STD-202 Method 103 Temperature: $85\pm 2^{\circ}\text{C}$ Relative Humidity: 85% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Exposure (Storage)		Refer to MIL-STD-202 Method 108 Temperature: $125\pm 3^{\circ}\text{C}$ / Relative Humidity: 0% Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Operational Life	Appearance: No damage Impedance change shall be within $\pm 30\%$ If the rated current of parts exceed 1A, the operating temperature should be 85°C .	Temperature: $125\pm 3^{\circ}\text{C}$ Applied Current: Rated Current/ Time: 1000hrs Measured after exposure in the room condition for 24hrs



Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	-	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

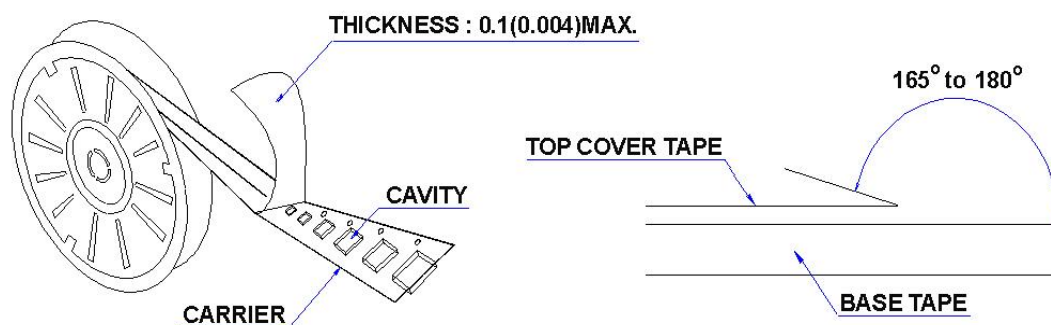
NOTE :

1. Re-flow possible times : within 2 times
2. Nitrogen adopted is recommended while in re-flow
3. Products can only be soldered with reflow

9 Packaging:

9.1 Packaging -Cover Tape

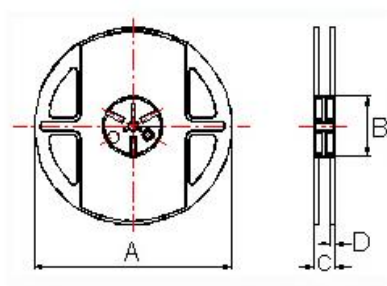
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



9.2 Packaging Quantity

TYPE	PCS/REEL
201610	3000

9.3 Reel Dimensions



Dimensions in mm

TYPE	A	B	C	D
201610	178	60	12	1.5

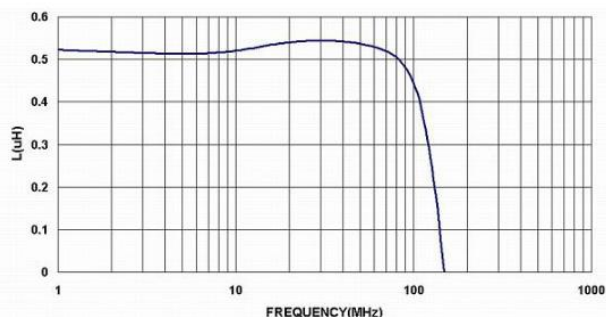
1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Do not knock nor drop.
3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
5. The moisture sensitivity level (MSL) of products is classified as level 1.

AKPB00201610 Series Specification

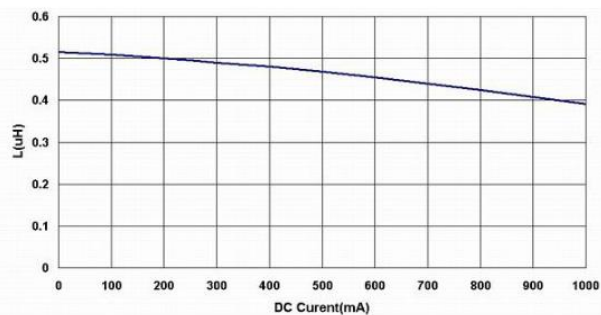
AEC-Q200

12 Graph:

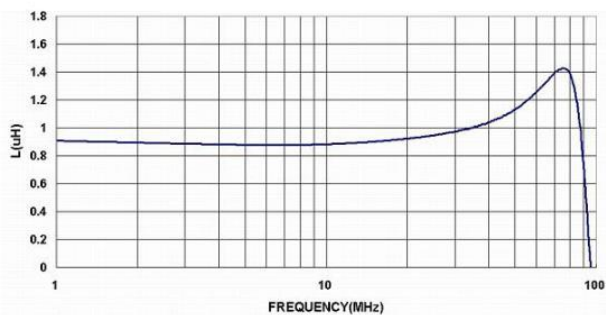
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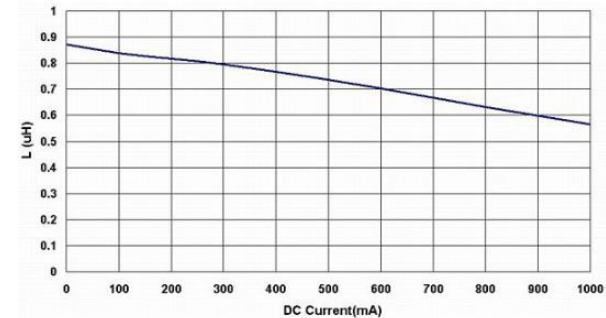
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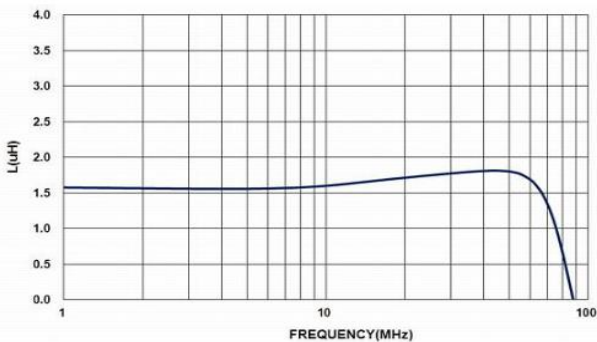
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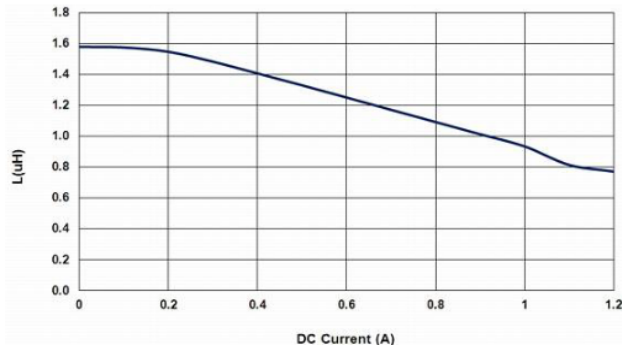
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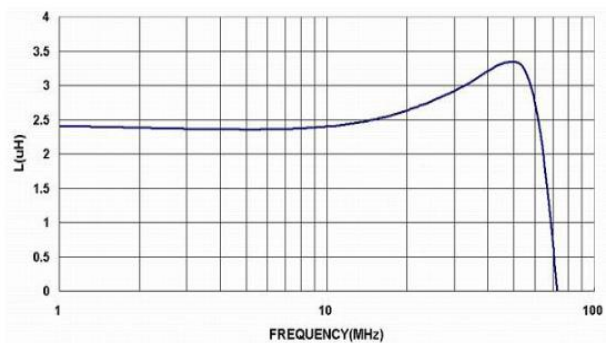
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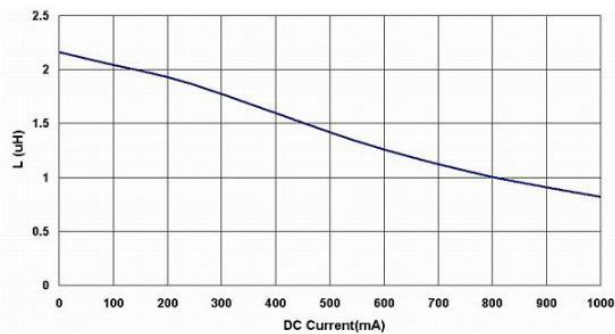
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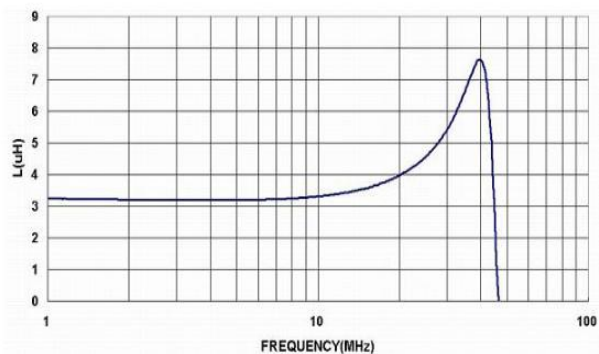


AKPB00201610 Series Specification

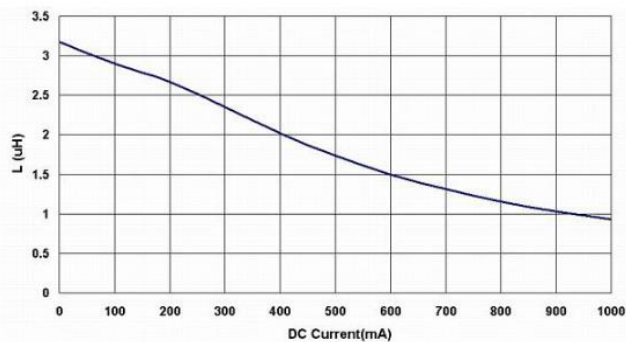
AEC-Q200

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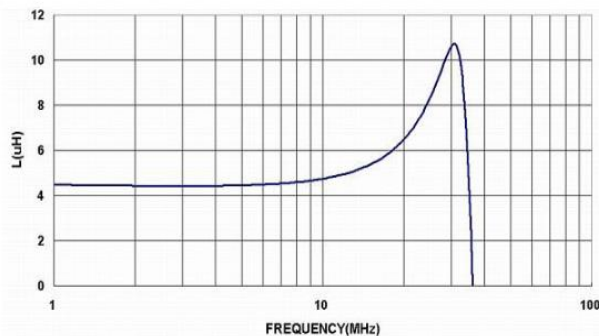
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AKPB002016103R3MA6



AKPB002016104R7MA6



AKPB002016104R7MA6

